*THERMALLY CONDUCTIVE EPOXY AND POLYIMIDE RESINS, ONE-COMPONENT**

REF	CURING SCHEDULE Recommended	POT LIFE	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
							BEFORE TG	AFTER TG		
E703FC	5 min at 125°C	4 h at 25°C	2,5 Pa.S	70-80°C	350°C	51%	$50\text{-}60.10^{-6}/°C$	$150\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Silicon chip bonding - Snap cure - Low volatiles
E703HV	5 min at 150°C	16 h at 25°C	10 Pa.S	70-80°C	> 350°C	51%	$50\text{-}60.10^{-6}/°C$	$150\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Silicon chip bonding - Very snap cure - Low volatiles - High viscosity
E703LF	1 min at 140°C	7 days at 25°C	10 Pa.S	70-80°C	> 350°C		$50\text{-}60.10^{-6}/°C$	$150\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Chip bonding - Perfectly adapted for the lead free solder resist
E703SC	5 min at 125°C	5 days at 25°C	12 Pa.S	70-80°C	> 350°C		$50\text{-}60.10^{-6}/°C$	$150\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Silicon chip bonding - Snap cure - Low volatiles - High viscosity
E704LF	1 min at 140°C	5 days at 25°C	7,5 Pa.S	70-80°C	350-380°C		$50\text{-}60.10^{-6}/°C$	$150\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Chip bonding - Perfectly adapted for the lead free solder resist
E707-2	30 min at 150°C	3 months at 25°C	8 Pa.S	90-100°C	370-390°C	42%	$40\text{-}50.10^{-6}/°C$	$120\text{-}150.10^{-6}/°C$	10^{13} Ω.cm	Single component of E707
E707-2FV	30 min at 150°C	5 days at 25°C	17 Pa.S	90-100°C	370-390°C	42%	$40\text{-}50.10^{-6}/°C$	$120\text{-}150.10^{-6}/°C$	10^{13} Ω.cm	Higher viscosity than E707-2
E707-2LF	30 min at 150°C	3 months at 25°C	12 Pa.S	90-100°C	> 380°C		$40\text{-}50.10^{-6}/°C$	$120\text{-}150.10^{-6}/°C$	10^{13} Ω.cm	Strain gauge bonding - Perfectly adapted for the lead free solder resist
E707-3	30 min at 150°C	3 months at 25°C	20 Pa.S	90-100°C	370-390°C		$55\text{-}65.10^{-6}/°C$	$130\text{-}160.10^{-6}/°C$	10^{13} Ω.cm	Protecting small electronic components by dipping
P101	1 h at 150°C + 1 h at 275°C	6 months at 25°C	11 Pa.S	175-205°C	576°C	60%	$25\text{-}27.10^{-6}/°C$	$48\text{-}50.10^{-6}/°C$	10^{13} Ω.cm	Polyimide resin. Insulating bonding - high temperature
P102	1 h at 150°C + 1 h at 275°C	6 months at 25°C	17 Pa.S	250-275°C	575°C				10^{13} Ω.cm	Polyimide resin. Insulating bonding - high temperature

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

* for more precision on the technical properties, to refer to the individual data sheet.

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épotecny

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